

**AMENDMENTS TO THE CLAIMS:**

**Listing of claims:**

This listing of claims replaces all prior versions and listings of claims in the application.

**1. (Original)** A manufacturing method of a multilayer wiring board, comprising:

a first step of mounting an electronic component on a frame resin layer including at least one of glass cloth, filler and nonwoven fabric, said frame resin layer including no electronic component therein; and

a second step of forming a resin layer by placing a semi-cured resin sheet on said frame resin layer so as to contact the mounted electronic component, and completely curing said semi-cured resin sheet with the electronic component buried there.

**2. (Original)** The manufacturing method as claimed in claim 1, wherein the semi-cured resin sheet includes fragments of at least one of filler and nonwoven fabric.

**Claim 3 (Cancelled).**

**Claim 4 (Cancelled).**